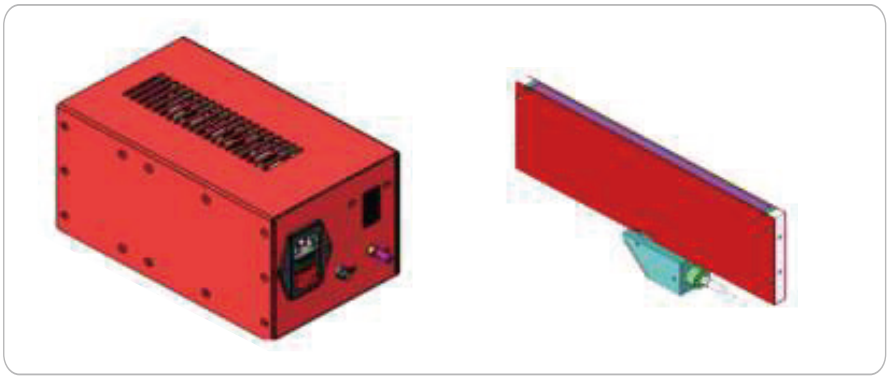
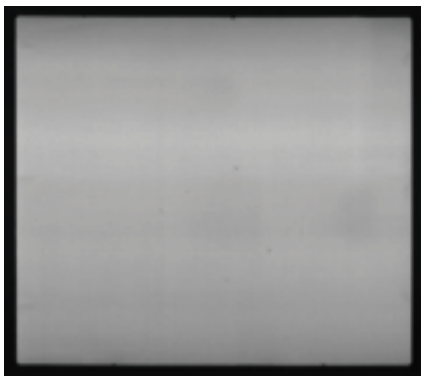
10W-1064-01 Silicon Transmission Series Detection Module





Camera capture diagram

Application Advantages

- The silicon transmission series detection module based on the laser penetration principle, enables real-time detection of microcracks and edge defects throughout the full production cycle.
- The laser head split version can be used with a high-definition line scan camera to detect microc-racks, edge defects and contaminants during silicon wafer production and texturing process stages.

Specifications

Parameter Unit	Unit	Parameter
Laser Type		450nm—100W
Model Number	W	15
Wavelength	nm	1064
Center Wavelength Deviation		±5
Average Power	W	15
Typical Working Distance	mm	10~25
Dimensions of the Optical Outlet	mm	280×10
Detectable Wafer Size	mm	≤230
Power Requirements	V	220

Parameter Unit	Unit	Parameter
IO Interface		White 0~24V+/ Black 0~0.5V-
Average Power Consumption	W	150
Outgoing Light Control Mode		Code SwitchIO Interface
Power Regulation Mode		Code Switch
Operating Temp.&Rh	°C	20~30；<80%
Controller Size	mm	218×122×111
Optical Module Size	mm	316×33×138
Weight	kg	≈4
Applicable Technology		Raw Silicon Wafers and Tufting Wafers